

A POLISHING PAD RESISTANT TO DELAMINATION

ABSTRACT OF THE DISCLOSURE

The present invention provides, chemical mechanical polishing pad with improved polishing properties and
5 longevity for polishing semiconductor wafers. The polishing pad comprises a thermoplastic backing film and a pressure sensitive adhesive coupled to the thermoplastic backing film. The pressure sensitive adhesive is configured to couple a chemical mechanical polishing pad to
10 a polishing platen. The pressure sensitive adhesive is further configured to provide an interface capable of substantially preventing delamination of the polishing pad from the polishing platen for at least about 4 days exposure to a polishing slurry medium having a pH of about
15 4 or higher.